

european space agency agence spatiale européenne

Pages 1 to 18

TERMS, DEFINITIONS, ABBREVIATIONS,

SYMBOLS AND UNITS

ESA/SCC Basic Specification No. 21300

space components coordination group

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DOCUMENTATION CHANGE NOTICE

Rev. Letter	Rev. Date	CHANGE Reference Item	Approved DCR No.
		This Issue supersedes Issue 3 and incorporates all modifications defined in the following DCR's:- Cover page DCN Para. 2.2.2 : "Complete failure" replaced by "loss" Para. 2.3.2 : Testing Level "B" statement added to Testing Levels Para. 4 : Specification numbers amended : ESA/SCC 21330 Title amended : ESA/SCC 21350 Title amended : ESA/SCC 2139020 added : ESA/SCC 2139020 added	None None 221083 21067 21057 21057 21057 21057 21057
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ABBREVIATIONS, SYMBOLS AND UNITS FOR GENERAL PURPOSES



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1. <u>SCOPE</u>

This specification defines the terms, definitions, abbreviations, symbols and units used in the ESA/SCC Basic, Generic and Detail Specifications which together form the overall SCC System.

Terms, definitions, abbreviations, symbols and units used for, and applicable to, individual components only are defined in ancillary Detail Specifications belonging to the 21300 series of specifications (see Section 4).

Each Detail Specification shall be read in conjunction with this specification.

2. TERMS AND DEFINITIONS FOR GENERAL PURPOSES

2.1 BASIC TERMS

2.1.1 <u>Classification</u>

Family of Components

Family of Structurally Similar Components - A group of components which display a particular and predominant physical characteristic and/or fulfil a specific function.

- A family of components that are structurally similar, but separately identifiable, covered by a single Detail Specification.

Such components shall be produced by one Manufacturer, consist of essentially the same materials and be manufactured according to the same basic design, processes and techniques. They shall differ only in electrical characteristics.

- Subfamily of Components A group of components belonging to the same component family and produced according to similar technological methods.
- Type and Style Type and style of a specific component are defined in the relevant Detail Specification.
 - A set of defined technologies subjected to Capability Approval review and limited by the capability boundaries.
 - One of the electrical, physical or mechanical parameters, design rules, materials, equipment or software forming the limits of the capability domain. These boundaries are proved initially and defined, by the Manufacturer, in the Process Identification Document.
- 2.1.2 <u>Specifications</u> Specification
 - Basic Specification

Capability Domain

Capability Boundary

procurement.
Such specification is applicable to all component families

A document containing the rules and requirements, including inspection procedures, applicable to component

- Such specification is applicable to all component families or a large group of components to the extent specified in the applicable Generic or Detail Specification.

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Generic Specification

- **Detail Specification** - A specification derived from a Generic Specification which covers a particular component or a recognised range of components. It describes that component, or range of components, together with rated and/or limit values and characteristics. A Detail Specification also includes inspection requirements or refers in respect of such requirements to the applicable Generic Specification. 2.1.3 Procedure Approval of a Manufacturer - A procedure which results in the recognition that a Manufacturer has a competent organisation for the production and inspection of particular components in accordance with the requirements laid down in ESA/SCC **Basic Specifications.** Qualification Approval Qualification approval is the decision by the proper authority that a particular Manufacturer can be considered as able to produce reasonable quantities of the component type which meets the specification requirements. Raw Material Lot - The material has to be manufactured: - With the same process, specifications and procedures. - With the same equipment. **Diffusion Lot** Wafers shall be processed within an uninterrupted period of 6 weeks:
 - With wafer raw material from the same crystal.
 - With the same process, specifications and procedures (diffusion).

- A specification applicable to a family or subfamily of components and containing all those requirements that are

common to a component family or subfamily.

- With the same design, construction and geometry (mask).
- With the same equipment.

Piece Parts Lot - The piece parts have to be manufactured:

- With the same process, specifications and procedures.
- With the same design, construction and geometry.
- With the same equipment.



-

Assembly Lot	 An assembly lot is a quantity of components or family of structurally similar components which, as well as their piece parts are manufactured:
	- With semiconductor dice out of one diffusion lot.
	- With basic raw material out of one raw material lot.
	- With piece parts out of one piece parts lot.
	- Through to the end of Final Production Tests.
	- With the same process, specifications and procedures.
	- With the same design, construction and geometry.
	- With the same equipment.
Inspection Lot	- A quantity of components presented for inspection and submission to lot-by-lot testing in accordance with the sampling document.
Delivery Lot	 A quantity of components delivered against an order and originating from the same assembly lot. It can include flight parts and Qualification/Lot Acceptance Test samples.
Selected Sublot	- A portion of an assembly lot, if the assembly lot comprises more units than are required for mechanical, environmental and endurance tests and delivery. A selected sublot shall consist of a minimum of the components necessary for delivery, test sublot and allowable failures during burn-in. More than one selected sublot can be extracted from an assembly lot.
Test Sublot	- A test sublot consists of those components that are required for the performance of mechanical, environmental and endurance tests according to the applicable Generic Specification. Such components shall be randomly taken from a selected sublot after successful completion of burn-in and parameter drift screening.
Deliverable Components	 Components to be delivered shall be processed and inspected according to the production flow chart and shall pass all tests specified for the required testing level.
Certificate of Conformity	 A document issued with a delivery lot, stating that the components have been taken from one or more inspection lots released in conformity with ESA/SCC basic rules.
Mark of Conformity	 A mark applied to the packing and/or component, indicating that the components originate from an inspection lot which has been released in accordance with ESA/SCC basic rules.

	See		Basic Specification lo. 21300	Rev. 'A'	PAGE 7 ISSUE 4	
	Capability Approval	-	An approval granted to established that his ca quality control of prod domain, fulfils ESA/SC	pability for design, ucts, within a defir	manufacture an	nd
	Chip Component	-	A component in its ultir	mate state of miniat	urisation.	
	Test Structure	-	An element or compon or more Parametric b and used in testing to c	oundaries of the c	apability domai	ne in
2.2	RELIABILITY CONCEPTS					
2.2.1	Reliability					
	Reliability (general definitio	ın) -	The ability of an item t stated conditions and fo			ər
	Reliability (probability defin	ition) -	The characteristic of a that it will perform a conditions and for a sta	a required functio	by the probabilit n under state	ty ed
2.2.2	Failure Concepts					
	Failure	-	The termination of the required function, of the characteristic of an ite item.	or excessive ch	ange of an	v
			A failure may be effe component during or conditions, or by wro insufficient or wrong do testing, storage or shipp	peration or storag ong handling of a ocumentation during	je within rate component, c	d of
	Failure Mode	-	The effect by which a fa	ailure is observed.		
	Sudden Failure	-	A failure that could not	be anticipated by p	rior examination	1.
	Gradual Failure	-	A failure that could be a	anticipated by prior	examination.	
	Partial Failure	-	A partial failure shall be	identified as a drift	or limit failure.	
	Drift Failure	-	A failure resulting fr beyond the specified pa and parameter drift s complete failure of the r	arameter drift value screening tests, b	s, during burn-i	'n
	Limit Failure	-	A failure resulting from beyond the specified required function.	om deviation in li limits and causing	characteristic(s) g failure of the) e

-

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Complete Failure	- A failure resulting fr	om deviations in	characteristic(s)

function.

beyond specified limits causing loss of the required

- **Catastrophic Failure** - A failure which is both sudden and complete. **Degradation Failure** - A failure which is both gradual and partial. Early Failure Period The early stages of a period which starts at a specified point in time and during which the failure rate decreases rapidly. Constant Failure Rate Period - A period during which it is possible that failures occur at an approximately uniform rate. Wear-out Failure Period - A period during which it is possible that the failure rate increases rapidly due to deterioration processes. Mean Failure Rate A quantity of items which is related to a time unit and which, having survived up to an arbitrary instant, are no longer active at the instant $t + \Delta t$. The instantaneous mean failure rate is equal to the density of the conditional probability of failure. Mean Time to Failure - MTTF - For truncated tests and during a defined life period of an item, the sum of the operating time of a population, divided by the total number of failures in the population during the period in given stress conditions (cumulative operating time is a product or sum of products). Mean Time Between Failures -MTBF - For a stated period in the life of an item, the mean value of the duration of operating times between consecutive failures under given stress conditions. Mean Life Observed Mean value of observed times to failure of all the individuals in a population of items under stated conditions. Failure Analysis - FA The logical, systematic examination of an item or its diagram(s) to identify and analyse the probability, causes and consequences of potential and real failures. Defect The nonfulfillment of an intended ESA/SCC requirement or a reasonable expectation, for the use of a component, including one concerned with safety.
- Minor Defect
 A defect that is not likely to reduce materially the usability of the unit of product for its intended purpose or its departure from established standards, having little bearing on the effective use or operation of the unit.
- Minor Defective A unit of product that contains one or more defects, but contains no critical or major defect.

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		1401 21000		
	Non-conformance	- The failure of a unit or requirements for any que		
2.2.3	Test Concepts			
	Qualification Test	 Qualification of a proc carried out on a numb the type with the object Manufacturer can be c products which meet th 	per of specimens t of determining wh onsidered capable	representative of ether a particular
	Screening Test	 A test, or combination unsatisfactory items or 	on of tests, inter those likely to exhi	nded to remove bit early failures.
	Burn-in	 Non-destructive testing an assembly lot and to effective or potential fai 	o screen good pai	characteristics of ts without either
	Final Production Test - FPT	- All test and measureme on all of the assembled		
	Environmental and Endurance Tests	 The testing (destructive product qualification put 	e or non-destructive rposes. Such testi	e) of samples for ng may include:
		- Shock.		
		- Vibration.		
		- Constant acceleration	า.	
		- Seal.		
		- Weldability.		
		- Solderability.		
		- Thermal shock.		
		- Moisture resistance.		
		- Terminal strength.		
		- Electrical measureme	ents.	
		- Operating life.		
		- High temperature sto	rage.	
	Extended Endurance Test	 Extended endurance to information about the re include: 	ests are tests realiability of a compo	quired to obtain nent. They may
		- Operating life, i.e. 10	000 hours	
		- High temperature i.e. 10 000 hours.	storage for a	a long time,
0.0	Destructive Physical Analysis - DPA	 Determination of the technology and process production of a partic suitability for Space standard of approved mage 	ses used by a Mar cular component applications, or t	nufacturer in the to establish its o maintain the
2.3	QUALITY ASSURANCE TERMS			

	Bee		Basic Specification	Rev. 'A'	PAGE 10
		Ν	lo. 21300		
2.3.1	General				
	Quality	-	The totality of characte bear on its ability to sat	ristics of an item of isfy stated and imp	r component that lied needs.
	Quality Assurance - QA	-	A planned and systema to provide adequate co conforms to established	onfidence that the	item or product
	Quality Control - QC	-	A management function or produced material preventing production o	is exercised for	the purpose of
	Qualification	-	The entire process by Manufacturers or Distri then identified in Qualifi	ibutors, examined	e obtained from and tested, and
	Qualified Part	-	A component type which the ESA/SCC requirem Qualified Parts List.	ch has been demo ents for inclusion	nstrated to meet in the ESA/SCC
	Safety	-	The state in which the damage arising from contended to an acceptate	omponent handling	(to persons) or or intended use
2.3.2	Statistics, Sampling and	Testing			
	Acceptable Quality Leve	el (A.Q.L.) -	The maximum percentanumber of defects per sampling inspection, can process average.	100 units) which, fo	r the purpose of
	Acceptance Number	-	The maximum number sample that will permit batch.	of defects or defe acceptance of the	ective units in a inspection lot or
	Rejection Number	-	The minimum number sample that will cause the sample.		
	Defects per 100 Units	-	The number of defects of a product is the num divided by the total re- quotient multiplied by possible in any unit equation:-	mber of defects c number of units 100 (1 or more	ontained therein of product, the defects being
			Defects per 100 units =	Number of defe	<u>cts x 100</u>
				Number of u	inits
	Inspection Level	-	An indication of the r amount of product.	elative sample si	ze for a given
	Inspection Tightened	-	Inspection under a sam level as for normal inspe acceptance criteria.	ipling plan using tl action, but requiring	ne same quality g more stringent

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Reduced Inspection	 Inspection under a sampling plan, using the same quality level as for normal inspection, but requiring a smaller sample for inspection.
100% Inspection	 Inspection in which specified characteristics of each unit of product are examined or tested to determine conformance to requirements.
Percent Defective Allowable - PDA	- The allowable percent defective of any given quantity of units of product is 100 times the number of defective units of product contained therein divided by the total number of units of product, i.e.:-
	Allowable percent defective = <u>Number of defectives x 100</u> Number of units inspected
Process Average	 Is the average percentage of defective or average number of defects per 100 units of product submitted by the supplier for original inspection.
Lot or Batch	- The term lot or batch shall mean "inspection lot" or "inspection batch", i.e. a collection of electronic components from which a sample is to be drawn and inspected to determine compliance with the acceptability criteria, and may differ from a collection of electronic components designated as a lot or batch for other purposes (e.g. production, shipment, etc.).
Lot Size	- The number of units of product in a lot.
Sample	- A sample consists of 1 or more electronic components from a lot or batch, the units of the sample being selected at random. The number of electronic components in the sample is the sample size.
Sample Size	- The number of units of product in the sample selected for inspection.
Sample Unit	- A unit of product selected to be part of a sample.
Unit of Product	- A unit of product is the thing inspected in order to determine its classification as defective or non-defective or to count the number of defects. It may be a single article, a pair, a set, a length, an area, an operation, a volume, a component of an end product, or the end product itself. The unit of product may, or may not, be the same as the unit of purchase, supply, production or shipment.
Sampling Frequency	 The sampling frequency 'f' is the ratio between the number of units of product randomly selected for inspection at an inspection to the number of product passing the inspection station.

		 	
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	Sampling Plan	 A statement of the sample size or sizes to be used ar the associated acceptance and rejection criteria. 	nd
	Resubmitted Lot	 A lot which has been rejected, subjected to eithe examination or testing, or both, for the purpose removing all defective units which may or may not be reworked or replaced, and submitted again for acceptance 	of be
	Testing	- Is an element of inspection and generally denotes the determination by technical means of the properties elements of supplies, or components thereof, includin functional operation, and involves the application established scientific principles and procedures.	of na
	Testing Levels	 Testing levels are identifiable qualities of component arrived at by prescribing the determination of testing Testing level 'B' is the highest defined level. 	ts g.
2.3.3	Inspection		
	Calibration	 Comparison of 2 instruments or measuring devices, 1 of which is a standard of known accuracy traceable to national standards, to detect, correlate, report or eliminate by adjustment any discrepancy in accuracy of the instrument or measuring device being compared with the standard. 	to te ne
	Measuring and Test Equipment	 All devices used to measure, gauge, test, inspec diagnose or otherwise examine materials, supplies an equipment to determine compliance with technica requirements. 	nd
	Attribute	 A characteristic or property which is appraised in terms of whether it does or does not exist (e.g. go or not go) wit regard to a given requirement. 	of th
	Inspection	- The examination and testing of supplies and service (including, when appropriate, raw materials, component and intermediate assemblies) to determine whether the conform to specified requirements.	ts
	Lot-by-lot Inspection	 Lot-by-lot inspection is that inspection carried out on eac lot either on a sample drawn from the lot or on th complete lot. The results of tests in this category ar used to determine whether the lot complies with the specified requirements. 	ie ′e
	Periodic Inspection	- Periodic inspection is that inspection carried ou periodically on a sample drawn either from an individual lo or from a number of lots. The lot(s) from which the sample is drawn shall have been shown to comply with the requirements for lot-by-lot inspection. The results from tests in this category are used to verify that the level of technical performance is being maintained.	ot ie ie m

		See
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2.3.4

Inspection by Attribute	 Inspection whereby either the unit of product or characteristic thereof is classified simply as defective or non-defective, or the number of defects in the unit of product is counted, in respect of a given requirement.
Inspection by Variables	 Inspection wherein certain quality characteristics of sample are evaluated in respect of a continuous numerical scale and expressed as precise points along this scale. Variables inspection records the degree of conformance or non-conformance of the unit with specified requirements
Inspection In-process	 for the quality characteristics involved. Inspection which is performed during the manufacturing or repair cycle in an effort to prevent defectives from occurring and to inspect the characteristics and attributes which are not capable of being inspected at final inspection.
Examination	- An element of inspection consisting of investigation, without the use of special laboratory appliances or procedures, of supplies and services to determine conformance to those specified requirements which can be determined by such investigations. Examination is generally non-destructive and includes, but is not limited to, visual, auditory, olfactory, tactile, gustatory and other investigations; simple physical manipulations; gauging; and measurement.
Traceability	- The means of knowing at all times during production or a specific period of utilisation of a component any historical detail of each production and reliability processing step, starting from the raw materials source, the inspector or worker, the state of the machine, etc.
<u>Documents</u>	
Inspection Record	- Recorded data concerning the results of inspection action.
Deviation	- Written authorisation, granted prior to the manufacture of an item, to depart from a particular performance or design requirement of a contract, specification or referenced document, for a specific number of units or specific period of time.
Waiver	- A written authorisation to accept a configuration item or other designated items which, during production or after having been submitted for inspection, are found to depart from specified requirements, but nevertheless are considered suitable for use "as is" or after rework by an approved method.
Inspection Quality Conformance	- All examinations and tests performed on items or services for the purpose of determining conformance with specified requirements.

Certificate of Conformance	 A Contractor's written statement, when authorised by contract, certifying that supplies or services comply with contract requirements.
Production Flow Chart	 The production flow chart is a drawing which shows the overall processing and testing, the manufacturing sequences of a particular part of production line, including inspection and process control points.
	N.B. Essential elements of the production flow chart are as follows:
	- Raw materials.
	- Processing steps.
	- Inspection.
	- Reference to all corresponding specifications with revision letter or number.
Overall Flow Chart	- The overall flow chart is a drawing which includes a simplified production flow chart, sequences of testing operations, indication of recorded data and documents to be delivered.
Qualified Parts List - QPL	 The qualified parts list is a list of components and materials accepted under the SCC Specification System, including the names and plant addresses of Manufacturers or distribution.
Survey, Product-oriented	 A review and evaluation to determine the adequacy of the technical requirements relating to quality and product conformance to design intent.
Authorised Representatives	 Representatives authorised in accordance with the Space Agency rules to act on its behalf in the National and European component fields.
Qualifying Space Agency - QSA	 The qualifying space agency is the national authority recognised by the SCCG inspection authority.
Process Identification Document - PID	 A Process Identification Document comprises all documents relevant to the manufacture of a specific component. It shall include, as a minimum:-
	(a) The production flow chart.
	(b) All process specifications.
	(c) All inspection procedures.
	(d) Constructional details of the component, including photographs where applicable.
	(a) The test programme

- (e) The test programme.
- (f) An organigram of the Manufacturer's organisation.



Capability Abstract

- A comprehensive synopsis of a capability domain in terms of technology boundaries, circuit function and performance, construction rules, package and design data etc. The document shall have no commercial sensitivity, thus rendering it suitable for inclusion in the Qualified Products List.

2.4 IRRADIATION TERMS

2.4.1 Irradiation In Orbit

The main influence on electronic components will be caused by:

- High energy electrons.
- Protons.
- Heavy ions.
- X-ray.
- Gamma ray.

2.4.2 Irradiation Resistance Testing

To assure the correct behaviour of a semiconductor device in a Space radiation environment, it is advisable to check its vulnerability to this environment by radiation stress testing in the laboratory. An exact radiation profile with all its different components and wide energetic spectrum cannot be duplicated in the laboratory. Instead of this, the influence of the radiation species, their energy and also the influence of the response of the semiconductor material and technology can be determined by experiments.

Though the particle type and dose rate, that may prevail, are disregarded, it is possible to determine behaviour under irradiation by dosage from a single radiation source. The effects of such a total dose bear a rough approximation to actual conditions for doses from approximately 1kRad up to 1MRad.

2.4.3 <u>The Basic Definitions</u>

The source of these definitions, units and parameters that are internationally accepted is IEC Publication 50:

- RAD : A dose of one RAD imparts 100 ERG of ionising exitation energy per gramme of material irradiated; 1 RAD (Si) = 100 ERG/g (Si).
- GRAY (GY) : 1 Joule/kg (100RAD).
- DOSE LEVEL : In RAD (material); 1RAD (Si) = 100 ERG/g (Si).
- DOSE RATE : In RAD (material)/sec.
- FLUENCE : Particles/cm².
- FLUX : Particles/cm²/sec.

2.4.4 Expressions used in ESA/SCC Basic Specification No. 22900

- Co 60 Source: A source with a steady state dose.
- Steady State Irradiation Testing: Testing the irradiation resistance of a component under a steady state (non-pulsating) source (A Cobalt 60 source for example).



- Total Dose Ionising Radiation: The amount of radiation that is absorbed by the component under test, expressed in RAD (Si) or GRAY (Si).
- In-situ Testing: Electrical testing of the component on the location where the component is irradiated.
- Remote Testing: Electrical testing of the component on another location than where the component is irradiated.
- Dosimetry: A method to measure the deposited energy or particle fluence in order to quantify the steady state radiation exposure.
- Faraday Cup: The most widely used instrument for monitoring the FLUX and FLUENCE and for absolute determination of charged particle fluxes. The total charge built up on the Faraday Cup divided by the charge per particle gives the total number of particles which have fallen on the cup.
- Device Biasing: The device under test has an outside voltage supplied during irradiation exposure.
- Unidirectional Incident Radiation: Exposure to a parallel (collimated) beam of radiation.
- Corrections for Source Decay: The irradiating source will change its fluence in time. Co-60 sources have a decrease with a half life of approximately 5 years.
- Annealing: Recovery of certain devices after removal of the irradiation source. This recovery to normal situation is called annealing.

3. ABBREVIATIONS, SYMBOLS AND UNITS FOR GENERAL PURPOSES

3.1 CURRENTS, VOLTAGES AND POWERS

l, i	=	Current	А	=	Ampère
V, v	=	Voltage	V	=	Volts
Р, р	=	Power	W	=	Watts

3.2 SUBSCRIPTS

AV, av	=	Average
F, f	=	Forward.

3.3 LETTER SYMBOLS FOR ELECTRICAL PARAMETERS

Symbol		Definition	<u>Unit</u>
B, b C G, g H, h L R, r X, x Y, y		Susceptance Capacitance Conductance Hybrid parameter Inductance Resistance Reactance Admittance	mhos Farad mhos Henry Ohm Ohm mhos
Z, z	=	Impedance	Ohm.

- 3.4 SUBSCRIPTS FOR ELECTRICAL PARAMETERS
 - l, i ≃ Input
 - O, o = Output.



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3.5 LETTER SYMBOLS FOR TEMPERATURE

- amb = Ambient
- case = Case
- J, j = Junction
- stg = Storage
- R_{th} = Thermal Resistance
- op = Operating.

3.6 OTHER SYMBOLS

t

f

- = Time
- = Frequency
- B = Bandwidth
- d = Distortion
- F = Noise figure
- G = Gain
- T = Temperature.

3.7 STANDARD VALUES

The standard values for 'E' ranges are shown in Appendix 'A'.

When an 'E' range is specified for a Range of Components in a Detail Specification, all values within the indicated range are available, within the limits specified.

The tolerance on values within each individual 'E' range will be as shown in Appendix 'A', unless otherwise stated in the Detail Specification.

4. ANCILLARY DETAIL SPECIFICATIONS

The following supplementary specifications have been issued:-

ESA/SCC 2133000	- Terms, Definitions, Abbreviations, Symbols and Units for Capacitors.
ESA/SCC 2133400	- Terms, Definitions, Abbreviations, Symbols and Units for Electrical Connectors.
ESA/SCC 2133600	- Terms, Definitions, Abbreviations, Symbols and Units for Electromagnetic Relays.
ESA/SCC 2134000	- Terms, Definitions, Abbreviations, Symbols and Units for Resistors.
ESA/SCC 2135000 (1)	 Terms, Definitions, Abbreviations, Symbols and Units for Discrete Non-Microwave Semiconductor Devices.
ESA/SCC 2139000	 Terms, Definitions, Abbreviations, Symbols and Units for Integrated Circuits.
ESA/SCC 2139020	 Terms, Definitions, Abbreviations, Symbols and Units for Charge Coupled Devices.

NOTES

1. For Discrete Microwave Semiconductor Devices (ESA/SCC Generic No. 5010), no individual ancillary specification for Terms, ... exists. ESA/SCC 2135000 should be used to the extent applicable.



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E12

±20% ±10% ±5.0%

E24

E48

±2.0%

E6

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APPENDIX 'A'

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E96

±1.0%

E192

±0.5%

715

732

796

825

STANDARD VALUES LIST

192	E6	E12	E24	E48	E96	E192
0.5%	±20%	±10%	±5.0%	±2.0%	±1.0%	±0.5%
100	220	220	220		221	221
101						223
02				226	226	226
04						229
105					232	232
106						234
107 109			040	237	237	237
110			240		243	240
111					243	243 246
13				249	249	240
14				210	240	252
115					255	255
117						258
18				261	261	261
20						264
21		270	270		267	267
123				274	074	271
26				2/4	274	_274 _277
27					280	280
129						284
130				287	287	287
132						291
133					294	294
35						298
37			300	301	301	301
38					000	305
40					309	309
43				316	316	312 316
45				510	310	320
47					324	324
49	330	330	330			328
50				332	332	332
52						336
54					340	340
56				0.10	0.10	344
58 60	1			348	348	348
62					357	352 357
64			360		357	361
65			000	365	365	365
67						370
69					374	374
72						379
74	1			383	383	383
76						388
78		390	390		392	392
80 82				400	400	397
82				402	402	402
87					412	407 412
89					-12	417
91				422	422	422
93						427
96			430		432	432
98						437
200				442	442	442
203				ļ		448
205				1	453	453
208				164	464	459
10	470	470	470	464	464	464
15	'''	7,0	-, v	ŀ	475	470 475
18					~~``	481
		[

E6	E12	E24	E48	E96	E192
±20%	±10%	±5.0%	±2.0%	±1.0%	±0.5%
100	100	100	100	100	100
				100	101
				102	102 104
			105	105	104
					106
				107	107
					109
		110	110	110	110
				110	111
				113	<u>113</u> 114
			115	115	115
				110	117
				118	118
	120	120	_		120
			121	121	121
				104	123
				124	124 126
			127	127	120
			127	121	129
		130		130	130
					132
			133	133	133
					135
				137	137
			140	140	<u>138</u> 140
			140	140	140
				143	142
					145
			147	147	147
					149
150	150	150		150	150
			154	154	152 154
			104	104	154
				158	158
		160			160
			162	162	162
					164
				165	165
			169	169	167 169
			105	105	172
				174	174
					176
			178	178	178
	180	180	l		180
				182	182
			187	187	184
			107	107	<u>187</u> 189
			ł	191	191
					193
			196	196	196
			l		198
		200		200	200
		-		205	203
			205	205	205 208
	I				EV0 1
			ŀ	210	
				210	210 213
			215	210 215	210